Report No. MCR-22-0255-B
October 01,2026

RELIABILITY REPORT

GROUP : RA4M2

DEVICE : R7FA4M2XXX

QUALITY GRADE : Standard

Quality Assurance Div.
Renesas Electronics Corporation

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Summary of Reliability Test Results for QFP Package (MSL3)

Test Item	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/231	3 lots or more
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/75	3 lots or more
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/75	3 lots or more
Temperature Humidity bias (HAST) (*1)	JESD22-A110	Ta=110 ℃, RH=85 %, Vccmax, 264 hrs	0/75	3 lots or more
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 500 cycles	0/75	3 lots or more
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500 V,1 time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (MSL3)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3) Peak Reflow Temp=260 °C	Pass	Verified after MSL preconditioning; applied to applicable reliability tests (*1).

Note :
- (*1) With preconditioning per JESD22-A113, MSL 3
- It is tested to confirm that all the samples are satisfied with an individual product specification.
- Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

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Summary of Reliability Test Results for QFN Package (MSL3)

Test Item	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 ℃, Vccmax, 1000 hrs	0/231	3 lots or more
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 ℃, 1000 hrs	0/75	3 lots or more
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/25	
Temperature Humidity bias (HAST) (*1)	JESD22-A110	Ta=110 ℃, RH=85 %, Vccmax, 264 hrs	0/75	3 lots or more
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 ℃ to 150 ℃ , 500 cycles	0/75	3 lots or more
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JESD22-C101	+/-500 V,1 time	0/3	Class: C2
Solderability (SD)	J-STD-002	245 ℃, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (MSL3)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3) Peak Reflow Temp=260 °C	Pass	Verified after MSL preconditioning; applied to applicable reliability tests (*1).

Note :
- (*1) With preconditioning per JESD22-A113, MSL 3
- It is tested to confirm that all the samples are satisfied with an individual product specification.
- Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

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The failure rate of the device in an actual use condition can be estimated by the below procedure.

・Equation for the failure rate estimation (λ)

$\lambda = \lambda b \times \pi T$ *(FIT)*

①Unique failure rate (λb)

λb= 0.007 FIT

Unique failure rate at Ta=55 ℃ using 60 % confidence level.

②Temperature term (πT)

$\pi T = exp\{11600 \times Ea \times (1/(273+55) - 1/(273+Ta))\}$

Ea： Activation energy（eV)
Ta： Ambient temperature（℃)

πT simplified chart as Ea=0.7 eV												
Ta (℃)	40	50	55	60	65	70	75	80	85	90	100	110
πT	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

・MTTF (Mean Time To Failure)

$MTTF = 1/\lambda$

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Reference about Renesas package code

Package type		Package code *1
Lead type plastic package	QFP	PxQP
	SOP	PxSP
Non-lead type plastic package	QFN	PxQN
Grid array type plastic package	BGA	PxBG
	LGA	PxLG
Wafer level chip scale package	WLCSP	SxBG

*1. First four digit

Table. Product list

No	Product part number	Package code	MSL	No	Product part number	Package code	MSL
1	R7FA4M2AB3CFL	PLQP0048K*	MSL3	51			
2	R7FA4M2AC3CFL	PLQP0048K*	MSL3	52			
3	R7FA4M2AD3CFL	PLQP0048K*	MSL3	53			
4	R7FA4M2AB3CFM	PLQP0064K*	MSL3	54			
5	R7FA4M2AC3CFM	PLQP0064K*	MSL3	55			
6	R7FA4M2AD3CFM	PLQP0064K*	MSL3	56			
7	R7FA4M2AB3CFP	PLQP0100K*	MSL3	57			
8	R7FA4M2AC3CFP	PLQP0100K*	MSL3	58			
9	R7FA4M2AD3CFP	PLQP0100K*	MSL3	59			
10	R7FA4M2AB3CNE	PWQN0048K*	MSL3	60			
11	R7FA4M2AC3CNE	PWQN0048K*	MSL3	61			
12	R7FA4M2AD3CNE	PWQN0048K*	MSL3	62			
13				63			
14				64			
15				65			
16				66			
17				67			
18				68			
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39				89			
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45				95			
46				96			
47				97			
48				98			
49				99			
50				100			

Note: MSL stands for Moisture Sensitivity Level.

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